Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	205	(Je with hyoung with Ryu) (Sung with jin with Lee) (Jun with ho with Lee) (Tae with gyu with Kim)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 14:17
L2	177028	SAMSUNG	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 14:17
L3	177137	1 2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 14:17
L4	6	3 and (match with plate) and (contact with module) and (radiator (heat with sink)) and semiconductor and (tester testing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:46
L5	3	3 and (match with plate) and (contact with module) and (radiator (heat with sink)) and semiconductor and (tester testing) and ((thermally thermal) with pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 14:21
L6	1	3 and (match with plate) and (contact with module) and (radiator (heat with sink)) and semiconductor and (tester testing) and ((thermally thermal) with pad) and (adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 14:22
L7	1	3 and (match with plate) and (contact with module) and (radiator (heat with sink)) and semiconductor and (tester testing) and ((thermally thermal) with pad) and (bond bonding glue adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 14:25
L8	1	3 and (match with plate) and (contact with module) and (radiator (heat with sink)) and (tester testing) and ((thermally thermal) with pad) and (bond bonding glue adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 14:25
L9	3	3 and (match with plate) and (contact with module) and (radiator (heat with sink)) and (tester testing) and ((thermally thermal) with pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 14:25

L10	2	3 and (match with plate) and (contact with module) and (radiator (heat with sink)) and semiconductor and (tester testing) and adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:03
L11	2	3 and (plate) and (contact with module) and (radiator (heat with sink)) and semiconductor and (tester testing) and adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:03
L13	3	3 and (match with plate) and (contact with module) and (radiator (heat with sink)) and semiconductor and (tester testing) and pad	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:58
L14	1	13 and (adhesive glue epoxy bond bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:48
L15	2	13 and (hole opening)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:48
L16	3	3 and (match with plate) and (contact with module) and (radiator (heat with sink)) and semiconductor and (tester testing) and ((thermally thermal) with pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:59
L17	10	(match with plate) and (contact with module) and (radiator (heat with sink)) and semiconductor and (tester testing) and ((thermally thermal) with pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:59